Great Place To Work® Certified AUG 2025-AUG 2026 INDIA

MOLD-TEK Packaging Limited

MTPL/SECT/03/2026-27 **Date: April 20, 2026**

To The Secretary, Listing Department, **BSE Limited,** Phiroze Jeejeebhoy Towers, Dalal Street, Fort, Mumbai-400001. **Scrip Code: 533080**	To The Manager, Listing Department, **National Stock Exchange of India Limited,** Exchange Plaza, 5th Floor, Plot No. C/1, G Block, Bandra Kurla Complex, Bandra (E), Mumbai-400051. **Symbol: MOLDTKPAC**

Sub: Outcome of Board Meeting

This is to inform you that the Board of Directors (“Board”) of the Company at its meeting held today i.e. April 20, 2026, has, inter-alia, considered and approved the First Interim Dividend of ₹ 2 /- (i.e. 40 %) per equity share of face value of ₹ 5/- each for the Financial Year 2025-26.

Further, as per our letter dated April 15, 2026, the Record Date for the purpose of ascertaining the eligibility of members for payment of interim dividend shall be Friday, April 24, 2026 and the interim dividend shall be duly paid within the stipulated timelines as prescribed under law.

The Board meeting commenced at 11:00 A.M. (IST) and concluded at 11:35 A.M. (IST).

This is for your kind information and records.

Thanking you,

Yours faithfully,
For Mold-Tek Packaging Limited

Harshita Suresh Chandnani
Digitally signed by Harshita Suresh Chandnani
Date: 2026.04.20 11:55:12 +05'30'

Harshita Suresh Chandnani
Company Secretary and Compliance Officer